Performance of the GridPix detector quad

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A B S T R A C T

A gaseous pixel readout module with four GridPix chips, called the quad, has been developed as a building block for a large time projection chamber readout plane. The quad module has dimensions 39.6 mm × 28.38 mm and an active surface coverage of 68.9%. The GridPix chip consists of a Timepix3 chip with integrated amplification grid and has a high efficiency to detect single ionization electrons, which enable to make a precise track position measurement. A quad module was installed in a small time projection chamber and measurements of 2.5 GeV electrons were performed at the ELSA accelerator in Bonn, where a silicon telescope was used to provide a reference track. The error on the track position measurement, both in the pixel plane and drift direction, is dominated by diffusion. The quad was designed to have minimum electrical field inhomogeneities and distortions, achieving systematics of better than 13 μm in the pixel plane. The resolution of the setup is 41 μm, where the total systematic error of the quad detector is 24 μm.

1. Introduction

In drift chambers charged particles are identified through ionization in the gas. For the readout of a time projection chamber (TPC) the finest granularity is offered by pixel readouts. In particular, a GridPix is a CMOS pixel readout chip with an integrated amplification grid added by MEMS postprocessing techniques [1,2]. As a result, single ionization electrons can be detected with great precision, allowing an excellent track position measurement and an estimate of the number of clusters for an energy loss (dE/dx) measurement for particle identification.

The original GridPix using the Timepix chip [3] has recently been succeeded by a GridPix based on the Timepix3 chip [4]. This newer chip offers superior timing, faster readout speed and the possibility to apply time walk corrections. The first results of a single chip detector have been analyzed and published in [5]. Electron diffusion in gas was found to be the dominant error on the track position measurement and systematics in the pixel plane remained below 10 μm. Using a truncated sum, an energy loss (dE/dx) resolution of 4.1 % was found for an effective track length of 1 m. The single chip detector was operated reliably in a test beam experiment. However, equipping a large detector surface poses an entirely new challenge.

In order to cover a large detector surface, it is practical to subdivide it into a number of standardized modules. Here we present the design of a quad module with four Timepix3 chips. Because the quad module has all services under the active area, it can be tiled to cover arbitrarily large areas. The performance of a TPC, read out by a single quad module was tested at the ELSA test beam facility in Bonn. Possible applications are in TPCs at future electron–positron colliders, other particle physics experiments and medical imaging such as proton therapy [3,6].

2. Quad detector design and construction

2.1. The Timepix3 based GridPix

Here the GridPix consists of a Timepix3 chip with an integrated grid. Directly on the surface of the Timepix3 chip, a 4 μm thick silicon-rich silicon nitride protection layer is deposited in order to prevent damage of the readout chip from discharges. On top of this 50 μm high SU8 pillars are attached that support the 1 μm thick aluminum grid that has 35 μm diameter circular holes aligned to the pixel input pads. The grid and dykes design was reoptimized: at four sides the grid ends on a solid SU8 dyke for which on two sides three readout columns were given up. The Timepix3 chip has a low equivalent noise charge (≈70 e−) and allows for a simultaneous measurement of the Time of Arrival (ToA) and the Time over Threshold (ToT) using a TDC (clock frequency 640 MHz) per pixel. For the readout, one out of the eight available links per chip is connected to a speedy pixel detector readout (SPIDR) board [7] at a speed of 80 Mbps. The hardware allows reading out at twice this speed.

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To provide a precise reference track, the quad TPC was sandwiched whole quad detector was mounted on a remotely controlled slider stage. Approximately 8W of power is consumed by carbon based materials. During low rate operation, the material budget can be further minimized by replacing the grids to maintain a homogeneous drift field. The grids are connected by 10 mm wide central guard electrode located 1.1 mm above the carrier plate. Finally, the wire bonds of the quad are filtered board, a U-shaped support is attached by thermally conductive glue under the carrier plate. The whole structure was put in a gas-tight container with a 40 mm high field cage to provide a homogeneous drift field. The cathode and guard voltages were set such that the electric field is limited secondary emission from the grid by UV photons produced between 2 × 3 planes of a Mimosa26 telescope [8], see Fig. 2. Each plane consists of a MAPS detector with 1152 × 576 pixels of size 18.4 μm × 18.4 μm.

A scintillator provided a trigger signal to the Trigger Logic Unit (TLU) [9] which numbers the triggers and subsequently directs them to both the SPIDR and telescope readout. The telescope hits were collected in time frames of 1.152 μs. Due to the high beam intensity, the telescope frames often contain hits from more than one track. The Timepix3 was operated in data driven mode with the trigger data merged in.

Because of the chosen limited link speed between the Timepix3 chips and the SPIDR a maximum of 1.3 MHit/s could be read out. This caused some hits to arrive late at the SPIDR readout, acquiring a wrong 409.6 μs course timestamp. As a work-around hits, up to 200 timestamps of 409.6 μs after the trigger were collected and analyzed. The first track hit had to arrive no more than 5 timestamps late, and the average course timestamp should not deviate more than 150 timestamps.

During data taking the 700 ml gas volume was flushed at a rate of 16.7 ml/min with premixed T2K TPC gas. This gas is a mixture consisting of 95% Ar, 3% CF₄, and 2% iC₂H₆O₄ suitable for large TPCs because of the relatively high drift velocity and the low diffusion in a magnetic field. The temperature and pressure were relatively stable at 300.5 K and 1011 mbar. The gas mixture contained a 814 ppm O₂ contamination and a 6000 ppm H₂O contamination, primarily due to the high gas permeability of a silicon rubber cable feed-through.

The cathode and guard voltages were set such that the electric field was 400 V/cm, which is close to the maximum drift velocity for the contaminated gas. The grid voltage was set to 330 V, at which there is limited secondary emission from the grid by UV photons produced in avalanches. The threshold level being a trade off between noise, sensitivity and time walk, was set to about 550 e−. The gain depends on the beam rate, because of charging up of the protection layer. During the high beam rate, the effective gain was approximately 1000. Some of the relevant run parameters are summarized in Table 1.

### 2.2. The quad module design and assembly

In order to cover large areas, the quad module shown in Fig. 1 was developed. Because of the complexity of the GridPix technology and the fragility of the grids, a small number of four chips per module was chosen. The chips are mounted on a common cooled base plate (COCA). They are electrically connected by wire bonds to a 6 mm wide PCB between the two pairs of chips. This allows the control and output lines to be directed to the backside of the quad to maximize the sensitive detection area. A short Kapton cable at the other side of the wire bond PCB provides a low impedance connection to the low voltage (LV) regulator. The grids are connected by 80 μm insulated copper wires to a high voltage (HV) filtering board. The connection to the common HV input uses a 100 MΩ resistor for each grid to rapidly quench a microdischarge. To support and cool the LV regulator board and the HV filtering board, a U-shaped support is attached by thermally conductive glue under the carrier plate. Finally, the wire bonds of the quad are covered by a 10 mm wide central guard electrode located 1.1 mm above the grids to maintain a homogeneous drift field.

The external quad dimensions are 39.6 mm × 28.38 mm of which 68.9% is active. In the present design the support components are made of aluminum contributing substantially to the material budget. In the future the material budget can be further minimized by replacing the aluminum by carbon based materials. During low rate operation, the module consumes 8 W of power of which 2 W in the LV regulator.

### 2.3. The quad detector

The quad module was embedded in a TPC consisting of a steel box and a 40 mm high field cage to provide a homogeneous drift field. The field cage is terminated on one end by the quad module fitted in a closely surrounding coppered frame at the grid potential, and on the other end by a solid cathode plate. The whole structure was put in a gas-tight container with 50 μm Kapton windows on two sides to minimize the material traversed by the beam.

### 3. Test beam measurement

The device was tested in October 2018 at the ELSA test beam facility in Bonn. The ELSA accelerator provided 2.5 GeV electrons at a rate of approximately 10 kHz during spills of 16.0 s in beam cycles of 17.1 s. The whole quad detector was mounted on a remotely controlled slider stage. To provide a precise reference track, the quad TPC was sandwiched between 2 × 3 planes of a Mimosa26 telescope [8], see Fig. 2. Each plane consists of a MAPS detector with 1152 × 576 pixels of size 18.4 μm × 18.4 μm.

### 4. Track reconstruction and event selection

#### 4.1. Track reconstruction procedure

Tracks are reconstructed as straight lines. The γ-axis is defined roughly in the direction of the beam, and the x-axis and z-axis are in...
The horizontal and vertical direction respectively. For the telescope, the \( y \)-coordinate is taken from the plane position, and the \( x \)-coordinate and \( z \)-coordinate correspond to the columns and rows. Apart from a small rotation, the \( x \) and \( y \)-coordinates correspond to the columns and rows of the GridPixes. The \( z \)-coordinate is the drift length calculated from the ToA and the drift velocity. Tracks are fitted using a linear regression fit with hit errors in the two directions perpendicular to the beam \( \sigma_x \) and \( \sigma_z \). The expressions for the error values are given in Sections 5.4 and 5.5.

The detectors are aligned using the data. First, the telescope is independently aligned. The positions in the \( y \)-direction along the beam are measured and kept fixed. Taking one plane as reference, the other five planes can be rotated. These rotations and additionally two shifts in \( x \)-direction and \( z \)-direction for four of the planes are iteratively determined from the fitted tracks. Next, the quad detector is aligned. Using iterative alignment each chip has three rotations and two shifts in the \( x \) and \( z \)-directions. Additionally, each chip has one parameter describing the angle in the \( xz \)-plane between the drift direction and the pixel plane.

An example event with a telescope track is shown in Fig. 3.

4.2. Selections

In the telescope a stringent selection is made to acquire a sample of clean tracks. At least 5 planes should have a hit and the hits should be within 50\( \mu \)m from the track. By requiring the slope difference of the track in the first three planes and in the last three planes to be smaller than 1 mrad, scattered tracks are rejected.

GridPix hits are considered if their ToA is within 500\( \mathrm{ns} \) of a trigger and their ToT is at least 0.15\( \mu \)s. The hits are collected using a track detected by the telescope as a seed. Outliers are rejected by requiring the residuals \( r \) (pulls \( r/\sigma \)) with respect to the telescope track to be smaller than 1.5 mm (2.0) in the \( x \)-direction and 2.0 mm (3.0) in the \( z \)-direction.

A track is rejected if it has less than 20 hits. Moreover the average position of all GridPix hits must be within 0.3 mm in the \( x \)-direction and \( z \)-direction of the telescope track. Given the high beam rate, the TPC often contains multiple tracks overlapping in time. To suppress overlapping tracks and to reject tracks with delta electrons, 80\% of the hits within 5 mm of a track are required to lie within a distance of 1.5 mm.

The selections are summarized in Table 2 and the total efficiency for events is about 12\%. Most events are rejected, because there are less than 20 GridPix hits corresponding to the telescope track.

5. Results

5.1. Number of hits

The distribution of the number of track hits per chip and the total number of track hits are shown in Fig. 4. The most probable number of hits per chip varies between 52 and 65 hits, and the mean varies between 65 and 80 hits. The most probable number of hits per quad is 131 and the mean number of track hits is 146 for an effective track length of approximately 27.5 mm. This is significantly below the calculated most probable value of 225 electron–ion pairs for a 2.5 GeV electron with this track length [10]. This is due to the too low effective grid voltage and possibly due to readout problems. Because of the low single electron efficiency, no energy loss (dE/dx) results were extracted.

5.2. Hit time corrections

To increase precision in the drift direction, the hit times were corrected. To correct for the double column structure and power distribution deformations of the Timepix3 chip, a ToT factor per column was extracted by injecting test pulses for each pixel. Furthermore, a ToA correction offset was determined from the test beam data based on the underlying substructure of 16 \( \times \) 2 pixels due to the clock distribution. In addition one ToA correction offset per column and one offset per row was applied. The ToT corrections are of \( \mathcal{O}(10\%) \) and the ToA corrections are of \( \mathcal{O}(1 \mathrm{~ns}) \).

5.3. Time walk correction

A hit is registered when the collected charge reaches the threshold. Since it takes longer for a small signal to reach the threshold than it does for a large signal, the measured ToA depends on the magnitude
of the signal. This effect is called time walk and can be corrected by using the ToT as a measure of signal magnitude. In Fig. 5 the mean of z-residuals is shown as a function of the ToT for all four chips. The relation can be parametrized using the time walk $\delta z_{\text{tw}}$ as a function of the ToT $T_{\text{ToT}}$:

$$\delta z_{\text{tw}} = \frac{c_1}{T_{\text{ToT}} + t_0},$$

where $c_1$ and $t_0$ are constants determined from a fit per chip.

5.4. Hit resolution in the pixel plane

The resolution of the single electrons in the transverse plane ($xy$) was measured as a function of the predicted drift position ($z$). Fig. 6 displays this relation for tracks crossing a fiducial region in the center of the chip. The resolution for the detection of ionization electrons $\sigma_z$ is given by:

$$\sigma_z^2 = \frac{d_{\text{pixel}}^2}{12} + D_T^2(z - z_0),$$

where $d_{\text{pixel}}$ is the pixel pitch size, $z_0$ is the position of the grid, and $D_T$ is the transverse diffusion coefficient. The resolution at zero drift distance $d_{\text{pixel}}/\sqrt{12}$ was fixed to 15.9 $\mu$m. Tracks with a $z$-position around 0.3 mm are given a larger error because they scatter on the central guard. Fitting expression (2) to the data gives a transverse diffusion coefficient $D_T$ of 398 $\mu$m/$\sqrt{\text{cm}}$ with negligible statistical uncertainty. The measured value is larger than the value of 270 $\mu$m/$\sqrt{\text{cm}} \pm 3\%$ predicted by the gas simulation software Magboltz [11]. Probably this is due to an inaccuracy in the gas mixing, which caused the CF$_4$ content to be lower than intended.

To compare the precision of the GridPix readout with the precision of conventional pad based TPC readouts, the resolution can be calculated over the length of one pad row. For example, at a drift distance of 4 mm the resolution of a single ionization electron is approximately 250 $\mu$m, so the resolution of a 6 mm track segment which has on average 32 electrons is therefore about 44 $\mu$m.

5.5. Hit resolution in the drift direction

The measured $z$-position is directly related to the drift velocity. Using the predicted positions from the telescope, the drift velocity is measured to be 54.6 $\mu$m/ns, which is slightly lower than the value of 59.0 $\mu$m/ns expected by Magboltz. Both values have negligible statistical uncertainties.

The resolution for the detection of ionization electrons $\sigma_z$ is given by:

$$\sigma_z^2 = \sigma_{\text{to}}^2 + D_L^2(z - z_0),$$

where $\sigma_{\text{to}}$ is the resolution at zero drift distance. The resolution as function of the drift distance is shown in Fig. 7 for tracks crossing the fiducial region. Since tracks with a $z$-position around 0.3 mm scatter on the central guard, these data points are given a larger error. The longitudinal diffusion coefficient $D_L$ was determined to be 212 $\mu$m/$\sqrt{\text{cm}}$ with negligible statistical uncertainty, which is equal to the expected value 212 $\mu$m/$\sqrt{\text{cm}} \pm 3\%$ from a Magboltz calculation.

5.6. Deformations in the pixel plane

It is important to measure possible deformations in the pixel plane ($xy$), because for applications in a TPC this affects the momentum resolution. Because of limited statistics, the mean transverse ($x$) residuals are calculated in bins of $4 \times 4$ pixels over the quad plane using the tracks defined by the telescope, see Fig. 8. Only bins with more than 800 entries are shown.

A distortion is present near the edges of the chips. The cause is twofold; firstly there is a geometrical bias at the edge of the detector because only part of the ionization cloud can be detected. Secondly, the grounded region at the edge of the Timepix3 die causes a non-uniformity of the electric field.

An empirically selected function of four Cauchy (Breit–Wigner) functions can be fitted to the geometrical bias and the non-uniformity of the field. Near the top and bottom edges the size of the deformations is different, as such – while keeping the other parameters fixed – a 4th
A similar measurement is done for distortions in the drift direction. In Fig. 11 the mean longitudinal ($z$) residuals are shown in bins of $4 \times 4$ pixels over the quad plane using the tracks defined by the telescope. Only bins with more than 800 entries are shown. As shown in Fig. 10, the r.m.s. of the distortion is $19 \mu m$ ($0.35$ ns) and $14 \mu m$ ($0.26$ ns) in the black outlined central area $2$ mm from the edges.

5.8. Quad detector resolution

The overall accuracy of a track position measurement using the quad detector can be tested by comparing the quad track to the telescope track. The difference will be a combination of statistical errors, systematic errors and multiple scattering contributions. Here it is important to estimate the systematical error, because multiple scattering occurs primarily outside the fiducial gas volume, and in applications with multiple quad modules the statistical errors will be further reduced.
A quad module with four Timepix3 based GridPixes has been designed and realized. The module has dimensions of 39.6 mm × 28.38 mm and an active surface of 68.9%. The quad module was embedded in a TPC detector and operated at the ELSA test beam facility. The single electron resolutions in the transverse and longitudinal planes are similar to the results obtained for the single-chip detector [5] and primarily limited by diffusion. It is shown that a systematic error from the quad detector for the distortions over the pixel plane of 13 μm (9 μm in the central region) has been achieved. The demonstrated resolution of the setup is 41 μm, of which the statistical error is 25 μm, the error caused by multiple scattering in the setup is 22 μm and the total systematic error is 24 μm.

The next step is to demonstrate a large detection area with the quad module as a building block and confirm the potential of the GridPix technology for large detectors. A new detector with 8 quad modules carrying a total of 32 Timepix3 GridPix chips is under construction.

Declaration of competing interest

The authors declare that they have no known competing financial interests or personal relationships that could have appeared to influence the work reported in this paper.

CRediT authorship contribution statement


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